PATENT ASSIGNMENT

SUBMISSION TYPE: NEW ASSIGNMENT

NATURE OF CONVEYANCE: ASSIGNMENT

CONVEYING PARTY DATA

<table>
<thead>
<tr>
<th>Name</th>
<th>Execution Date</th>
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</thead>
<tbody>
<tr>
<td>Cheng-Hsien WU</td>
<td>01/13/2011</td>
</tr>
<tr>
<td>Chih-Hsin KO</td>
<td>01/13/2011</td>
</tr>
<tr>
<td>Clement Hsingjen WANN</td>
<td>01/18/2011</td>
</tr>
</tbody>
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RECEIVING PARTY DATA

Name: TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address: No. 8, Li-Hsin Rd. VI, Hsinchu Science Park
City: Hsinchu
State/Country: TAIWAN
Postal Code: 300

PROPERTY NUMBERS Total: 1

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<th>Property Type</th>
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<tr>
<td>Application Number</td>
<td>13009151</td>
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CORRESPONDENCE DATA

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Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
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ATTORNEY DOCKET NUMBER: T5057-B355U

NAME OF SUBMITTER: Benjamin J. Hauptman

Total Attachments: 1
source=efiledassign#page1.tif
ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

1) Cheng-Hsien WU
2) Chih-Hsin KO
3) Clement Hsingjen WANN

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD., having a place of business at No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 101 in the invention entitled

SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD WITH IMPROVED EPITAXIAL QUALITY OF III-V COMPOUND ON SILICON SURFACES

(a) for which an application for United States Letters Patent was filed on 1-19-2011, and identified by United States Patent Application No. 13/009,151; or

(b) for which an application for United States Letters Patent was executed on ________.

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Cheng-Hsien Wu  
   Name: Cheng-Hsien WU  
   Date: 2011.1.13

2) Chih-Hsin KO  
   Name: Chih-Hsin KO  
   Date: 2011.1.13

3) Clement Hsingjen WANN  
   Name: Clement Hsingjen WANN  
   Date: 2011.1.13